



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C220JB8NCNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>220</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>C</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

① Se	eries	Samsung Multi-layer Ceramic Capacitor									
② Si	ize	0603	(inch co	ode)	L:	1.6	± 0.1	mm	W:	0.8 ± 0.1	mm
③ Di	ielectric	C0G				(8)	Inner el	octrodo	N	li	
_						•			-	•	
4 Ca	apacitance	22	рF				Termina	ition	C	u	
⑤ Ca	apacitance	±5	%				Plating		S	n 100%	(Pb Free)
to	olerance					9	Product	:	Н	ligh-Q	
6 Ra	ated Voltage	50	V			10	Special		R	eserved for	future use
7 Tr	hickness	0.8	± 0.1	mm		11)	Packagi	ing	С	ardboard Ty	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	840 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 $^{\circ}\!$						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)				
Moisture	Capacitance change :	With rated voltage				
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q: 173.33 min					
	IR : 500Mohm or 25Mohm $\cdot \mu$ F					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature				
	Q: 330 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25 °C				
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.